

ELECTRONIC DEVICES AND ITS PRODUCTION METHODS

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ABSTRACT OF THE DISCLOSURE

An electronic device having mounted thereon an MEMS element or other functional elements, in which a device body and lid define an element-carrying space, the element-carrying space is sealed air-tight by an ultrasonic bonded part bonding the device body and the lid, and the element-carrying space having arranged inside it a system element secured to the device body and/or the lid by flip-chip connection.